



Material Content Data Sheet



Sales Product Name		IPB80N06S2L-05		Issued		29. August 2013		
MA#		MA000275849						
Package		PG-TO263-3-2		Weight*		1468.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.294	0.84	0.84	8374	8374
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		581	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174	
	non noble metal	copper	7440-50-8	851.691	58.01	58.09	580109	580864
wire	non noble metal	aluminium	7429-90-5	5.346	0.36	0.36	3641	3641
encapsulation	organic material	carbon black	1333-86-4	8.702	0.59		5927	
	plastics	epoxy resin	-	95.722	6.52		65199	
	inorganic material	silicondioxide	60676-86-0	475.712	32.40	39.51	324020	395146
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6577	6577
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	noble metal	silver	7440-22-4	0.192	0.01		131	
	non noble metal	tin	7440-31-5	0.154	0.01		105	
	non noble metal	lead	7439-92-1	7.350	0.50	0.52	5006	5242
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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